
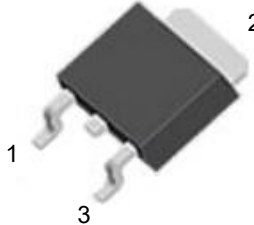
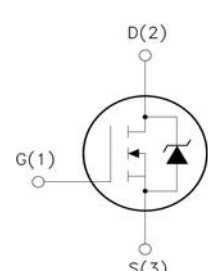


<p style="font-size: 1.2em; margin: 0;">XXW5N50</p> <p>Features:</p> <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances. <input type="checkbox"/> Excellent Switching Characteristics. <input type="checkbox"/> Extended Safe Operating Area. <input type="checkbox"/> Unrivalled Gate Charge :Qg=13nC (Typ.). <input type="checkbox"/> V_{DSS}=500V, I_D=5A <input type="checkbox"/> R_{DS(on)} : 1.4Ω (Max) @V_G=10V <input type="checkbox"/> 100% Avalanche Tested 	<p style="text-align: center;">TO-252</p> <div style="text-align: right;">  </div> <div style="text-align: center;">  </div> <div style="text-align: center;">  </div> <div style="text-align: right; margin-top: 10px;"> <p>1.Gate (G)</p> <p>2.Drain (D)</p> <p>3.Source (S)</p> </div>
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Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V _{DSS}	Drain-Source Voltage	500	V
I _D	Drain Current	T _j =25°C	A
		T _j =100°C	
V _{GSS}	Gate-Source Voltage	±30	V
E _{AS}	Single Pulse Avalanche Energy (note1)	270	mJ
I _{AR}	Avalanche Current (note2)	5.0	A
P _D	Power Dissipation (T _j =25°C)	25	W
T _j	Junction Temperature(Max)	150	°C
T _{stg}	Storage Temperature	-55~+150	°C
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	°C

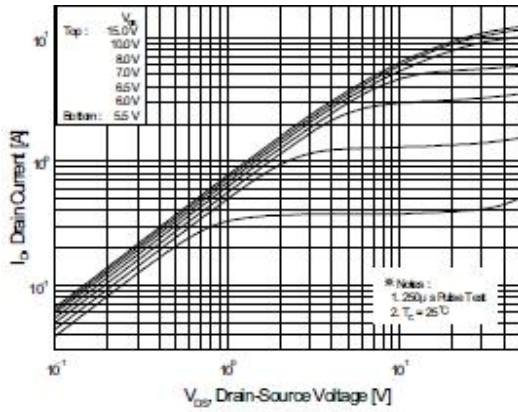
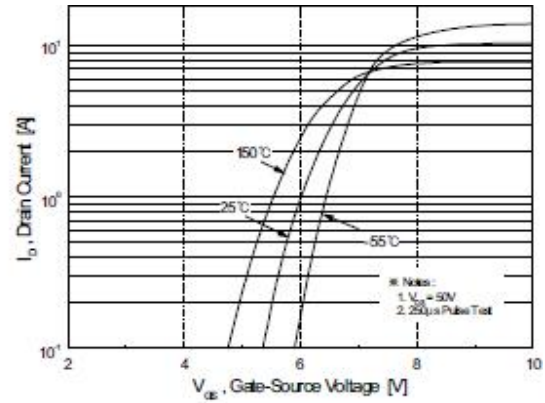
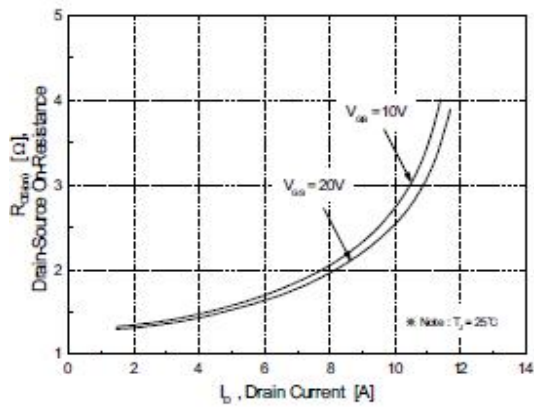
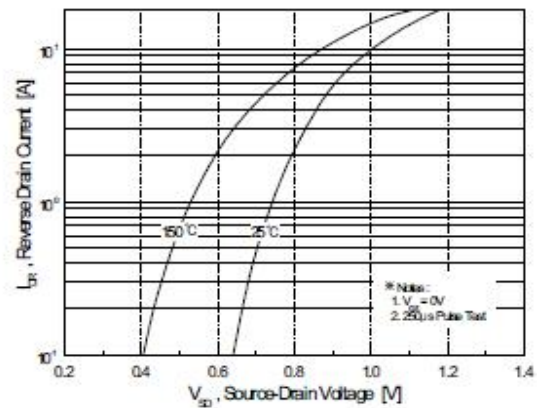
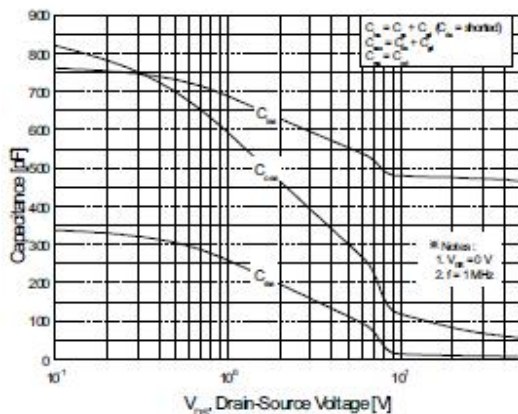
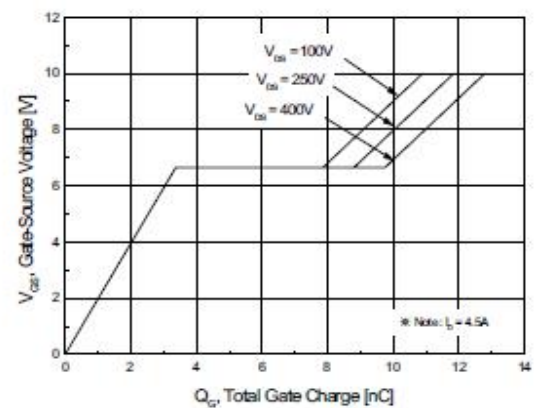
Thermal Characteristics

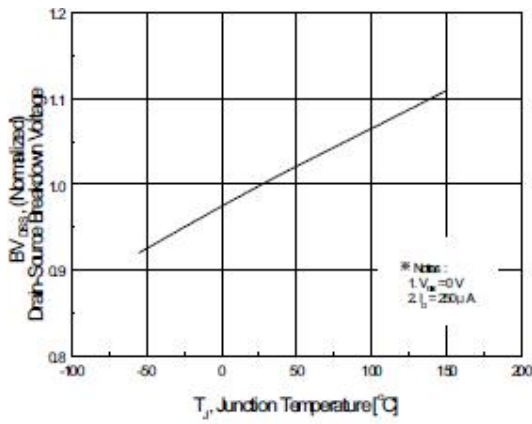
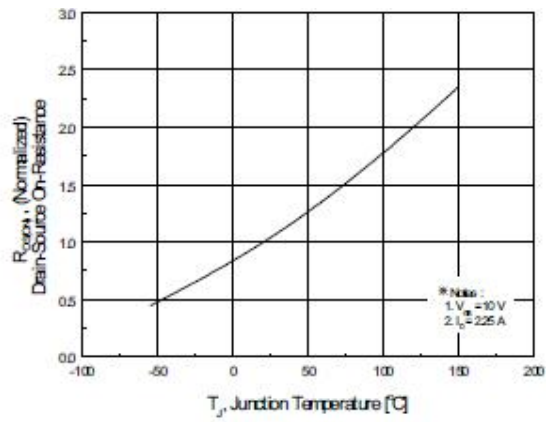
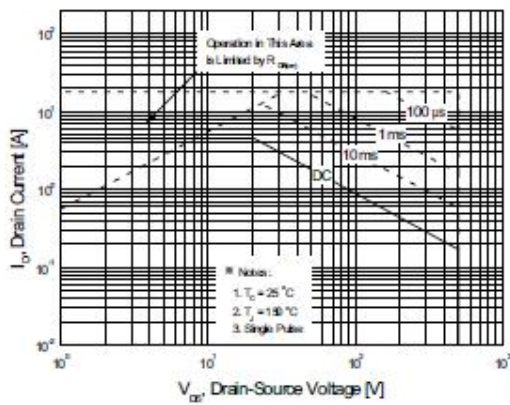
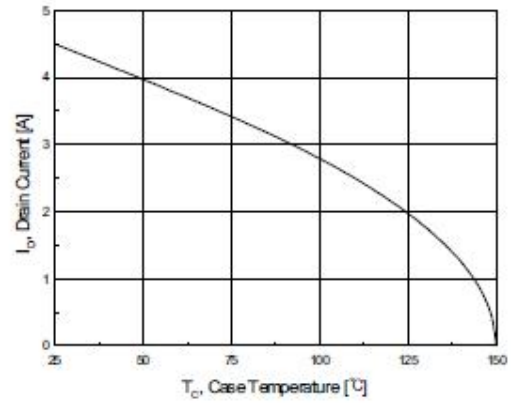
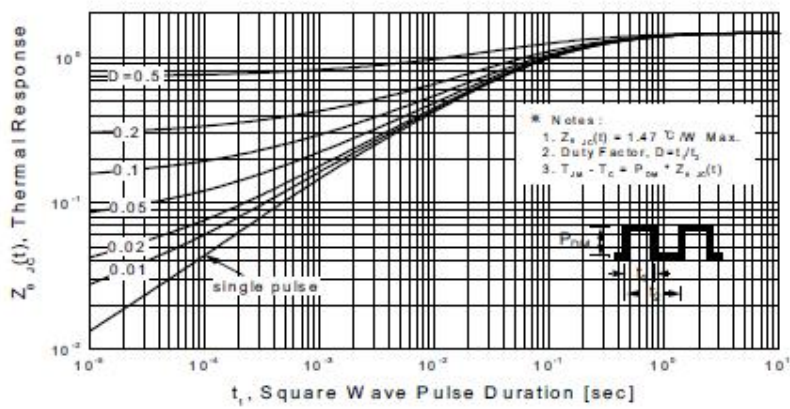
Symbol	Parameter	Typ.	Max.	Unit
R _{θJC}	Thermal Resistance, Junction to Case	-	3.45	°C/W
R _{θJA}	Thermal Resistance, Junction to Ambient	-	110	°C/W

Electrical Characteristics (Ta=25°C unless otherwise noted)

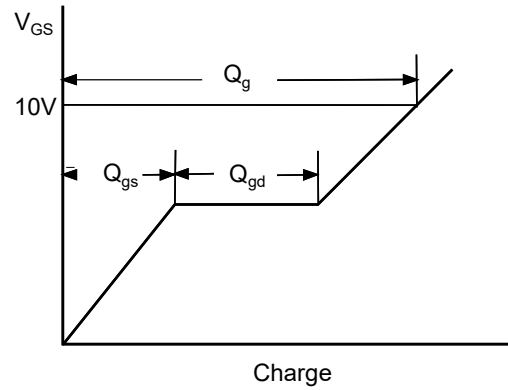
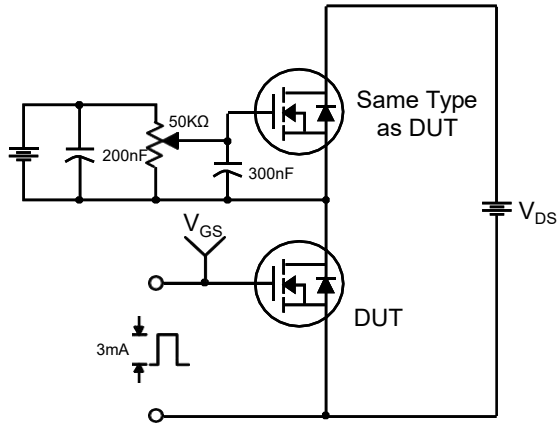
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0	500	-	-	V
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D =250μA, Reference to 25°C	-	0.47	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =500V, V _{GS} =0V	-	-	1	μA
		V _{DS} =400V, T _J =125°C	-	-	10	
I _{GSSF}	Gate-body leakage Current, Forward	V _{GS} =+30V, V _{DS} =0V	-	-	100	nA
I _{GSSR}	Gate-body leakage Current, Reverse	V _{GS} =-30V, V _{DS} =0V	-	-	-100	
On Characteristics						
V _{GS(TH)}	Date Threshold Voltage	I _D =250μA, V _{DS} =V _{GS}	2	-	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	I _D =2.5A, V _{GS} =10V	-	-	1.4	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0, f=1.0MHz	-	620	-	pF
C _{oss}	Output Capacitance		-	70	-	
C _{rss}	Reverse Transfer Capacitance		-	8	-	
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	V _{DD} =250V, I _D =5A R _G =25Ω (Note 3,4)	-	13	35	ns
T _r	Turn-On Rise Time		-	55	120	
T _{d(off)}	Turn-Off Delay Time		-	25	60	
T _f	Turn-Off Rise Time		-	35	80	
Q _g	Total Gate Charge	V _{DS} =400V, V _{GS} =10V, I _D =5A (Note 3,4)	-	13	17	nC
Q _{gs}	Gate-Source Charge		-	3.4	-	
Q _{gd}	Gate-Drain Charge		-	6.4	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Max. Diode Forward Current	-	-	-	5.0	A
I _{SM}	Max. Pulsed Forward Current	-	-	-	20	
V _{SD}	Diode Forward Voltage	I _D =5A	-	-	1.5	V
T _{rr}	Reverse Recovery Time	I _S =5A, V _{GS} =0V diF/dt=100A/μs	-	215	-	nS
Q _{rr}	Reverse Recovery Charge	(Note3)	-	1.26	-	μC

- Notes : 1, L=27mH, I_{AS}=5A, V_{DD}=50V, R_G=25Ω, Starting T_J=25°C
 2, Repetitive Rating : Pulse width limited by maximum junction temperature
 3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%
 4, Essentially Independent of Operating Temperature

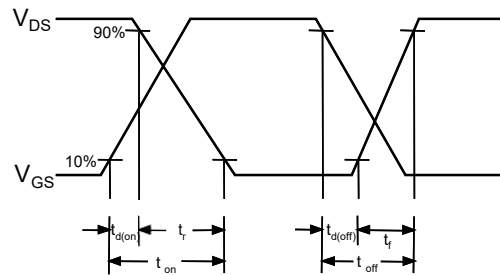
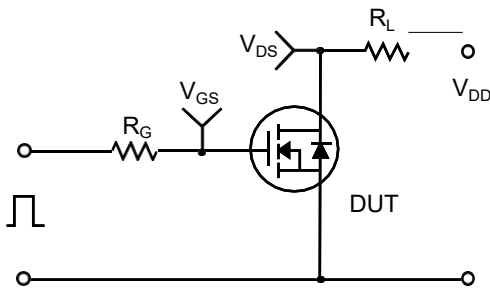
Typical Characteristics

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics

Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Transient Thermal Response Curve

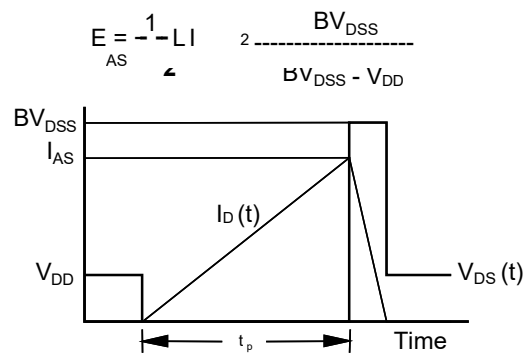
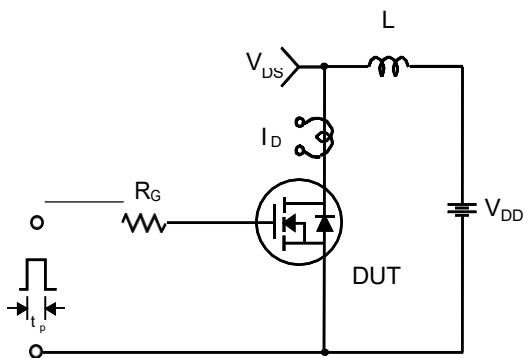
Gate Charge Test Circuit & Waveform



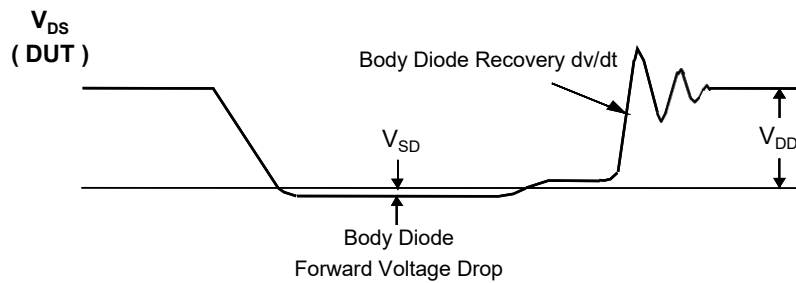
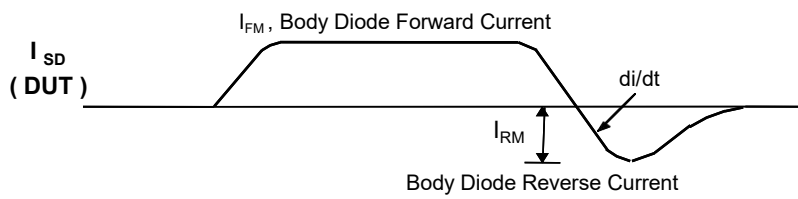
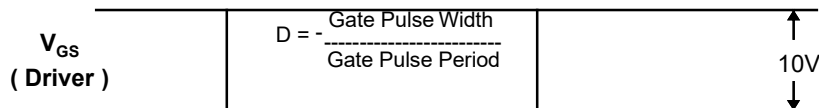
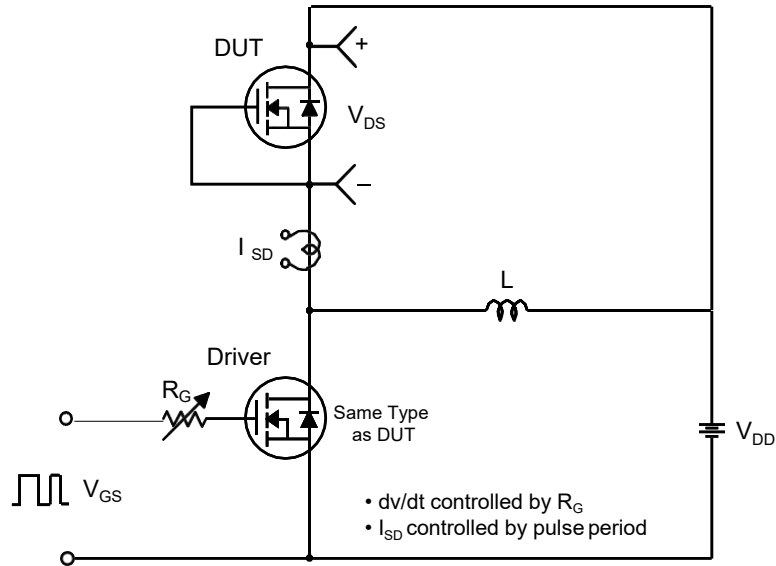
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



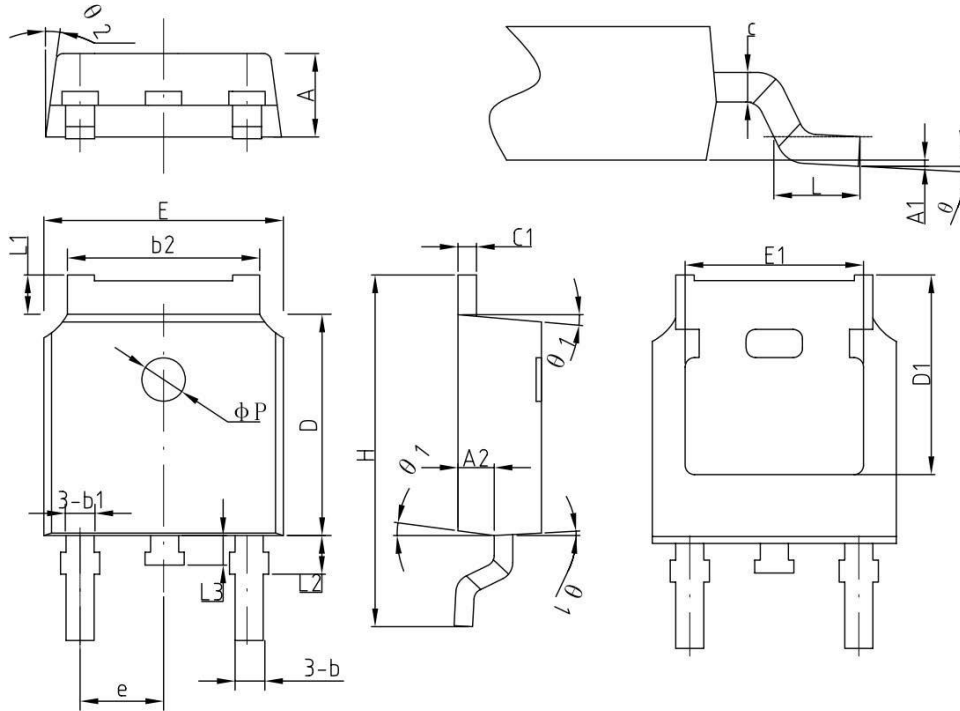
Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimension

TO-252

Unit: mm



COMMON DIMENSIONS
 (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	2.2	2.30	2.38
A1	0	—	0.10
A2	0.90	1.01	1.10
b	0.71	0.76	0.86
b1		0.76	
b2	5.13	5.33	5.46
c	0.47	0.50	0.60
c1	0.47	0.50	0.60
D	6.0	6.10	6.20
D1	—	5.30	—
E	6.50	6.60	6.70
E1	—	4.80	—
e	2.286BSC		
H	9.70	10.10	10.40
L	1.40	1.50	1.70
L1	0.90	—	1.25
L2		1.05	
L3		0.8	
ϕP		1.2	
θ	0°	—	8°
$\theta 1$	5°	7°	9°
$\theta 2$	5°	7°	9°